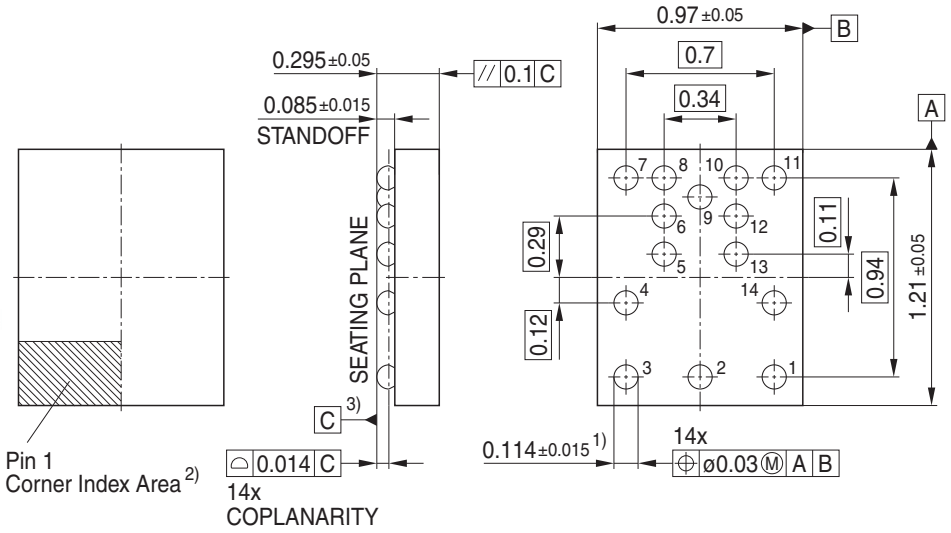
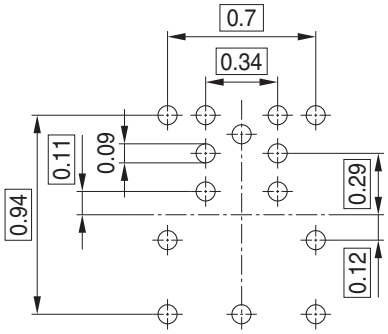
Package Outline



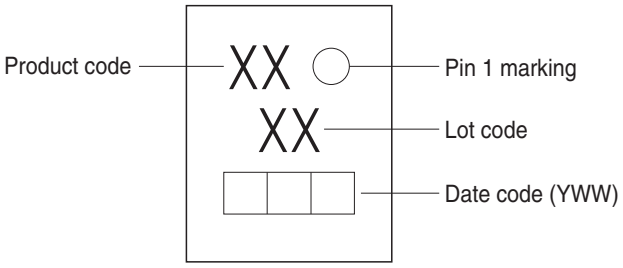
1) Dimension is measured at the maximum solder ball diameter, parallel to primary datum C
2) Pin 1 corner identified by marking
3) Primary datum C and seating plane are defined by the domed crowns of the balls

Foot Print

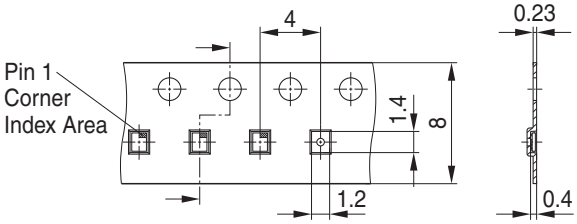
Soldering Type: Reflow Soldering



Marking Layout



Tape and Reel



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